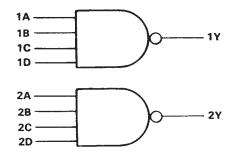
- Package Options Include Ceramic Chip Carriers and Flat Packages in Addition to Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

### description

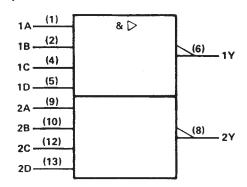
These devices contain two independent 4-input positive-NAND 50-ohm line drivers. They perform the Boolean function  $Y = \overline{ABCD}$ .

The SN54S140 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74S140 is characterized for operation from 0°C to 70°C.

### logic diagram (each driver)



### logic symbol†



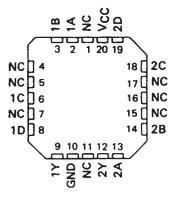
<sup>&</sup>lt;sup>†</sup>This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN54S140 . . . J OR W PACKAGE SN74S140 . . . D OR N PACKAGE (TOP VIEW)

1A[[	U14 VCC
1B 🗆 2	13 2D
NC □3	12 <b>]</b> 2C
1C ☐ 4	11DNC
1D <b>□</b> 5	10 2B
17□6	9 🕽 2A
GND 7	8 <b>] 2</b> Y

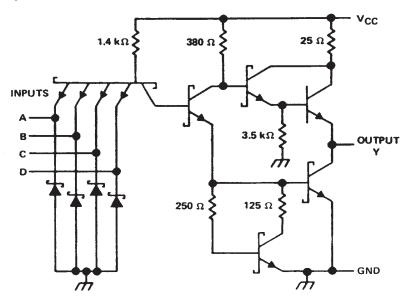
SN54S140 . . . FK PACKAGE (TOP VIEW)



NC-No internal connection

SDLS210 - DECEMBER 1983 - REVISED MARCH 1988

### schematic (each driver)



Resistor values shown are nominal.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V <sub>CC</sub> (see Note 1)	7 V
Input voltage	
Operating free-air temperature range: SN54'	
SN74'	
Storage temperature range	– 65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



### recommended operating conditions

			SN54S140			SN74S140			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc :	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧	
V <sub>IH</sub>	High-level input voltage	2			2			٧	
VIL	Low-level input voltage			0,8			0.8	V	
Іон І	High-level output current			- 40			- 40	mA	
lo <sub>L</sub>	Low-level output current			60			60	mA	
TA	Operating free-air temperature	- 55		125	0		70	°C	

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

BADAMETER		TEST COMPL			SN54S1	40				
PARAMETER		TEST CONDIT	HUNST	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V <sub>CC</sub> = MIN,	I <sub>I</sub> = - 18 mA				- 1.2			- 1.2	V
\/-··	V <sub>CC</sub> = MIN,	V <sub>IL</sub> = 0.8 V,	I <sub>OH</sub> = - 3 mA	2.5	3.4		2.7	3,4		V
VOH	V <sub>CC</sub> = MIN,	VIL = 0.5 V,	$R_O = 50 \Omega$ to GND	2			2			)
VOL	V <sub>CC</sub> = MIN,	V <sub>1H</sub> = 2 V,	I <sub>OL</sub> = 60 mA			0.5			0.5	V
lį	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 5.5 V				1			1	mA
11Н	V <sub>CC</sub> = MAX,	V <sub>IH</sub> = 2.7 V				0.1			0.1	mA
Iις	V <sub>CC</sub> = MAX,	V <sub>IL</sub> = 0.5 V				- 4			- 4	mA
los §	V <sub>CC</sub> = MAX			- 50		- 225	- 50		- 225	mA
1ссн	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0 V			10	18		10	18	mA
<sup>1</sup> CCL	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 4.5 V			25	44		25	44	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	MIN TYP	MAX	UNIT	
tPLH			D -03 O	C = 50 = 5	4	6.5	ns
t <sub>PHL</sub>	0.7.4	V	R <sub>L</sub> = 93 Ω,	C <sub>L</sub> = 50 pF	4	6.5	ns
tPLH	Any	1	D -02.0	0 - 150 - 5	6		ns
tPHL			$R_{L} = 93 \Omega$ ,	C <sub>L</sub> = 150 pF	6		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ} \text{C}$ .

<sup>§</sup> Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed 100 milliseconds.





6-Feb-2020

### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
JM38510/08101BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 08101BCA	Samples
JM38510/08101BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 08101BDA	Samples
JM38510/08101BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 08101BDA	Samples
M38510/08101BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 08101BCA	Samples
M38510/08101BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 08101BCA	Samples
M38510/08101BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 08101BDA	Samples
M38510/08101BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 08101BDA	Samples
SN54S140J	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SN54S140J	Samples
SN54S140J	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SN54S140J	Samples
SN74S140D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	S140	Samples
SN74S140D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	S140	Samples
SN74S140DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	S140	Samples
SN74S140DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	S140	Samples
SN74S140DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	S140	Samples
SN74S140DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	S140	Samples
SN74S140N	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	0 to 70	SN74S140N	Samples
SN74S140N	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	0 to 70	SN74S140N	Samples



### PACKAGE OPTION ADDENDUM

6-Feb-2020

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74S140NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	74S140	Samples
SN74S140NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	74S140	Samples
SNJ54S140FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S 140FK	Samples
SNJ54S140FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S 140FK	Samples
SNJ54S140J	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SNJ54S140J	Samples
SNJ54S140J	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SNJ54S140J	Samples
SNJ54S140W	ACTIVE	CFP	W	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SNJ54S140W	Samples
SNJ54S140W	ACTIVE	CFP	W	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SNJ54S140W	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



### PACKAGE OPTION ADDENDUM

6-Feb-2020

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN54S140, SN74S140:

Catalog: SN74S140

Military: SN54S140

NOTE: Qualified Version Definitions:

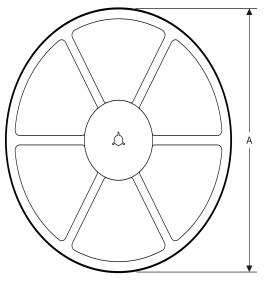
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

## PACKAGE MATERIALS INFORMATION

www.ti.com 14-Jul-2012

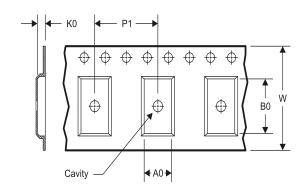
### TAPE AND REEL INFORMATION

### **REEL DIMENSIONS**





### **TAPE DIMENSIONS**



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### TAPE AND REEL INFORMATION

### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74S140DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74S140NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

**PACKAGE MATERIALS INFORMATION** 

www.ti.com 14-Jul-2012



### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74S140DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74S140NSR	SO	NS	14	2000	367.0	367.0	38.0

# W (R-GDFP-F14)

## CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# FK (S-CQCC-N\*\*)

## LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



### **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
  Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
  Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



# D (R-PDSO-G14)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



# D (R-PDSO-G14)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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